REV LETTER: E PAGE NO: 1 OF 1 PART NUMBER:

Polymer PTC Devices

Surface mount fuses

Shanghai Wayon Thermo/Electro Materials Co.,Ltd.

4th Floor, No.201, New Jinqiao Road, Shanghai 201206,ChinaTel: 86-21- 5032016158995165Fax: 86-21-50320266E-mail: market@way-on.comHttp://www.way-on.com



LP-MSM050

Features

- □ Small size of 1812
- □ Fast tripping resettable circuit protection
- □ Surface mount packaging for automated assembly
- Agency Recognition: UL、CSA、TUV PLus III



Product Dimensions (mm)

Part number —	Α	В	С	D	E	
	Max.	Max.	Max.	Max.	Min.	
LP-MSM050	4.73	3.41	0.61	0.60	0.30	
- D B			Part Marking S	ystem		
Marking			w ——	- Product family		
	Ĩ.					
				-Current rating		

Electrical Characteristics

Dent number	l _Η	Ι _Τ	V _{max}	I _{max}	T _{trip})	Pd _{typ}	R _{min}	R _{1max}
Part number	(A)	(A)	(V)	(A)	Current(A)	Time(S)	(W)	()	()
LP-MSM050	0.50	1.00	15	40	8.0	0.15	1.0	0.15	1.00

 I_{H} =Hold current: maximum current at which the device will not trip at 25 still air.

I_T=Trip current: minimum current at which the device will always trip at 25 still air.

V_{max}=Maximum voltage device can withstand without damage at rated current.

Imax=Maximum fault current device can withstand without damage at rated voltage.

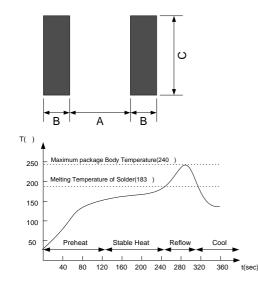
T_{trip}=Maximum time to trip(s) at assigned current.

Pd_{typ}=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

R_{min}=Minimum device resistance at 25 prior to tripping.

R_{1max}=Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number -	Α	В	С	
Fart number	(mm)	(mm)	(mm)	
LP-MSM050	3.45	1.78	3.15	

* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tape & Reel: 2000pcs per reel.